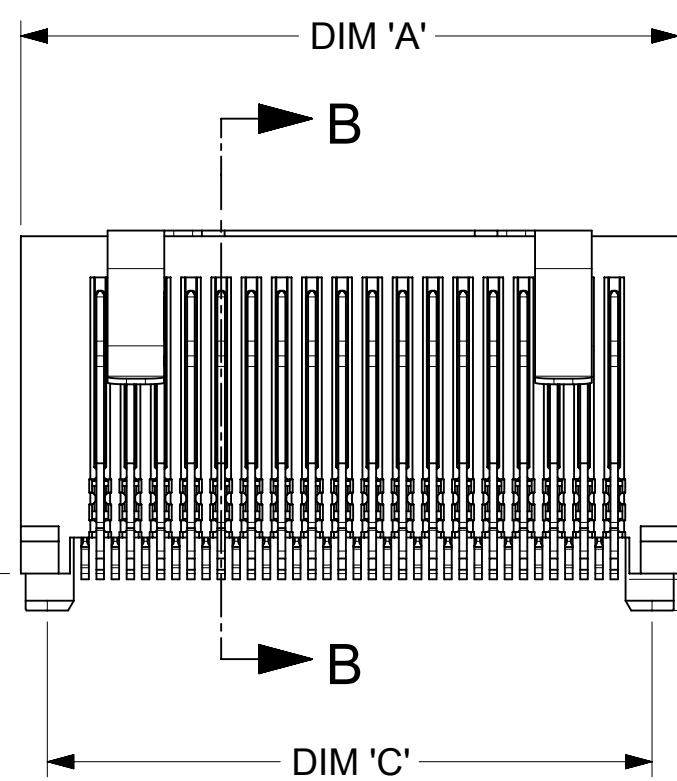
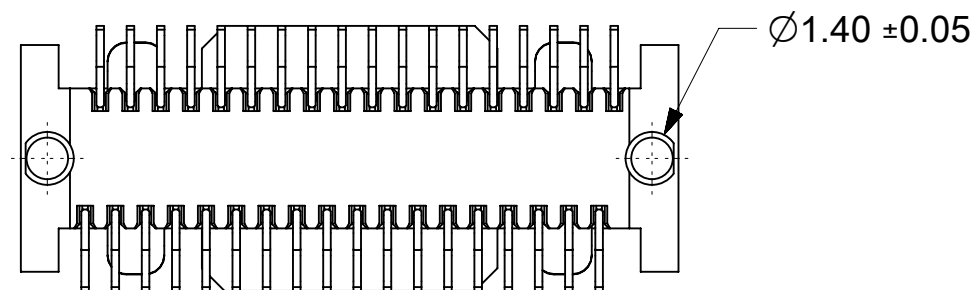


36 CIRCUIT ASSEMBLY SHOWN

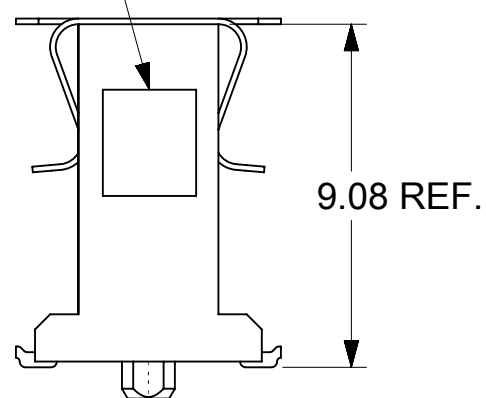


E  
SEE NOTE 3

0.83

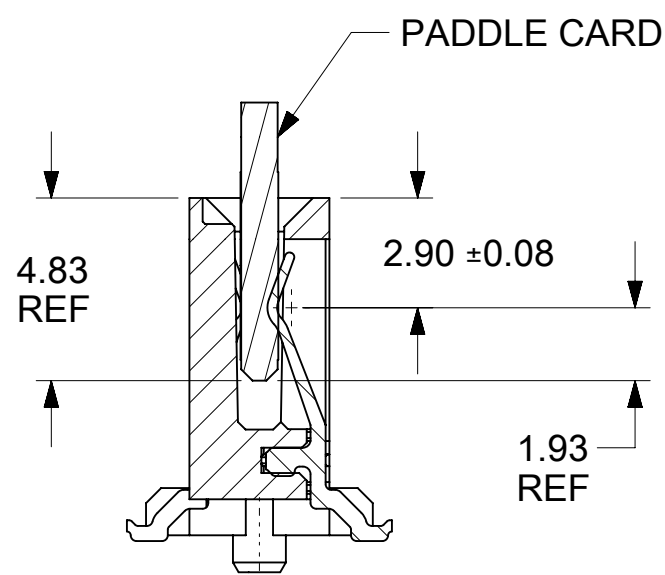


DATE CODE LOCATION  
SEE NOTE 4

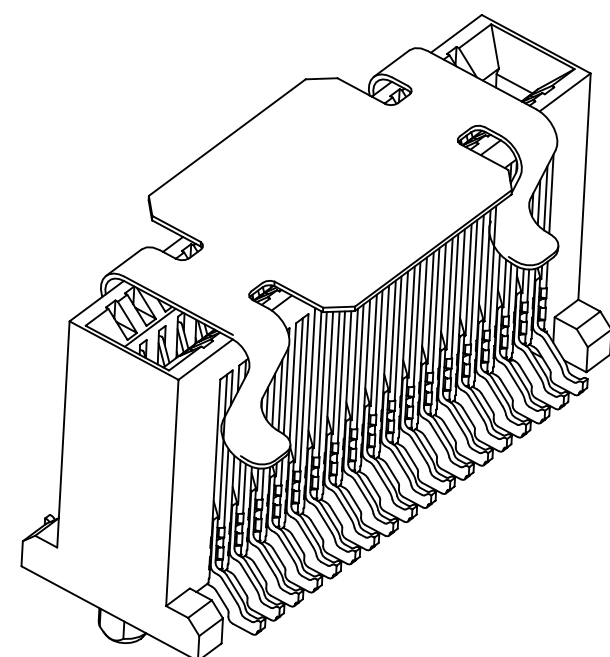


NOTES:

1. MATERIAL:  
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK  
TERMINALS - COPPER ALLOY
2. TERMINAL PLATING:  
OPTION 1  
CONTACT AREA: 0.38µm HARD GOLD OVER 2.54µm NICKEL  
SOLDER AREA: 2.54-5.09µm TIN OVER 1.27µm NICKEL  
OPTION 2  
CONTACT AREA: 0.76µm HARD GOLD OVER 2.54µm NICKEL  
SOLDER AREA: 2.54-5.09µm TIN OVER 1.27µm NICKEL
3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/.004 MEASURED FROM FRONT HOUSING STANDOFF (DATUM E)
4. DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)
5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
6. MATES WITH:  
A. INTERNAL CABLE SERIES:  
79575/74563/79576/74573/79536/74562/74569/74586  
B. PADDLE CARD PCB: DO NOT BOTTOM OUT PCB IN THE CONNECTOR. SEE SECTION Z-Z.  
USE WITH APPROPRIATE INTERNAL SHELL FROM SD-76010-002
7. LITTLE ROCK PACKAGING PER PK-75577-001  
CHENGDU PACKAGING PER PK-75577-002
8. CONFORMS TO PRODUCT SPECIFICATION PS-75783-001
9. CONFORMS TO APPLICATION SPECIFICATION AS-75783-001



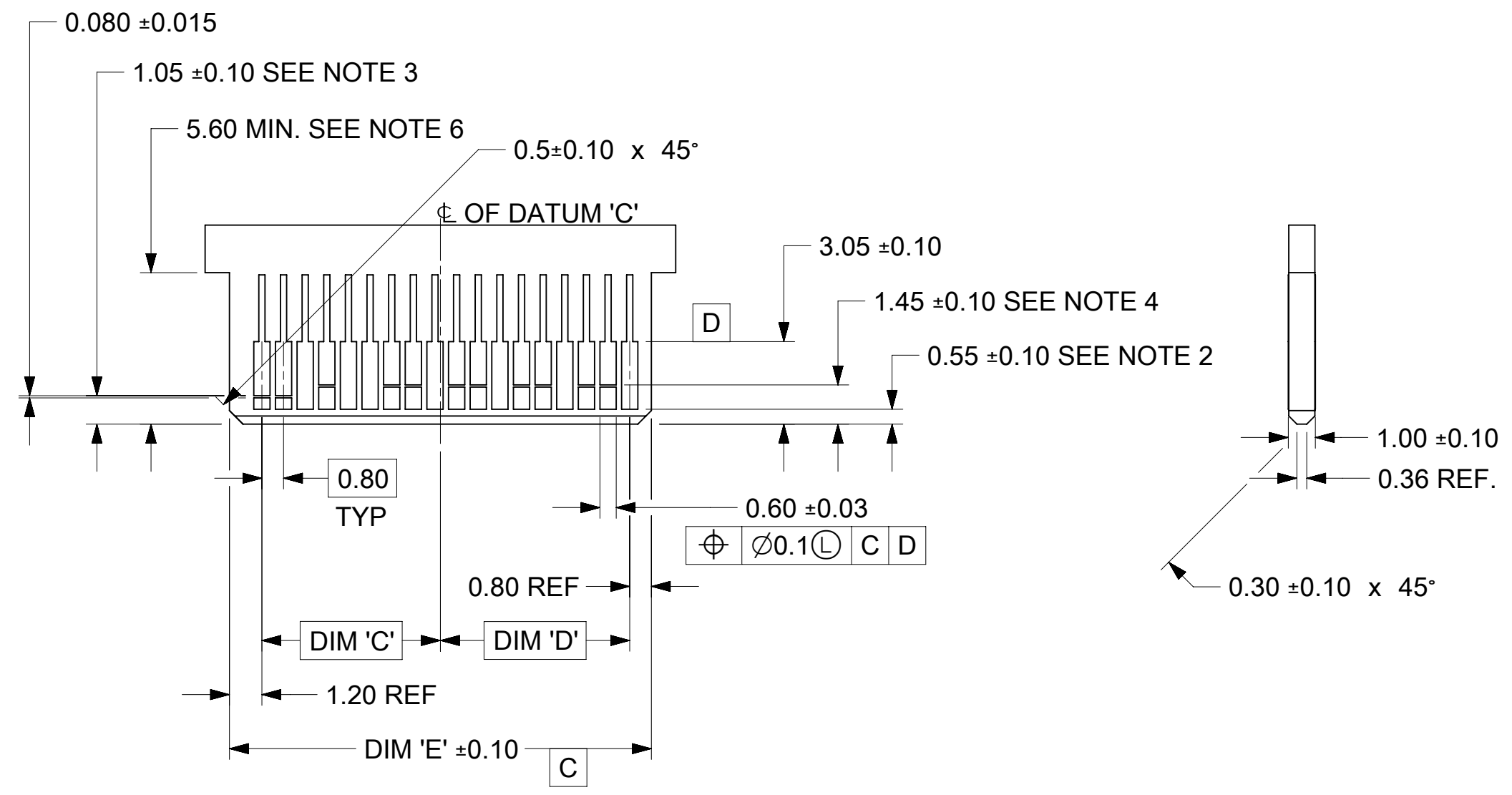
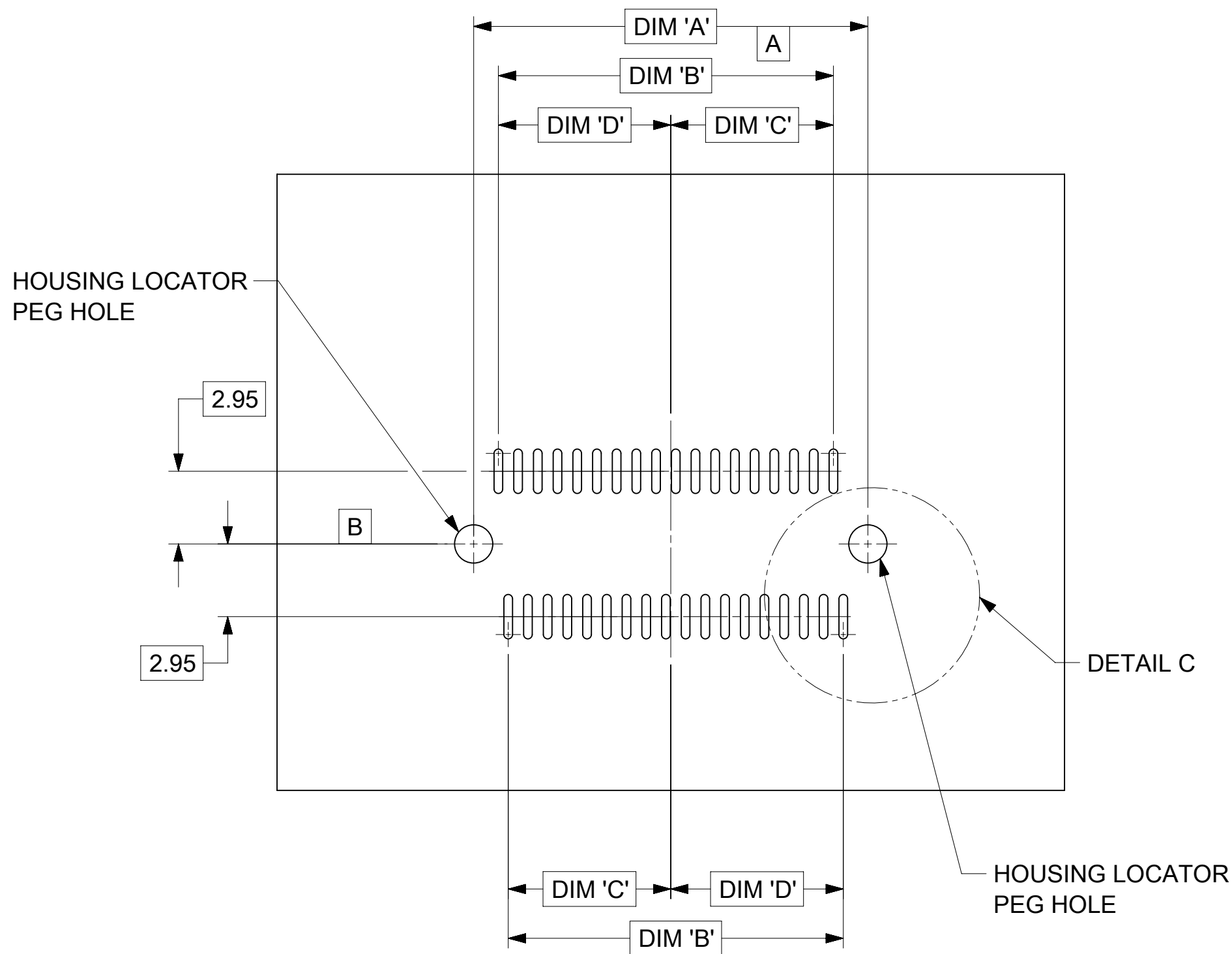
SECTION B-B



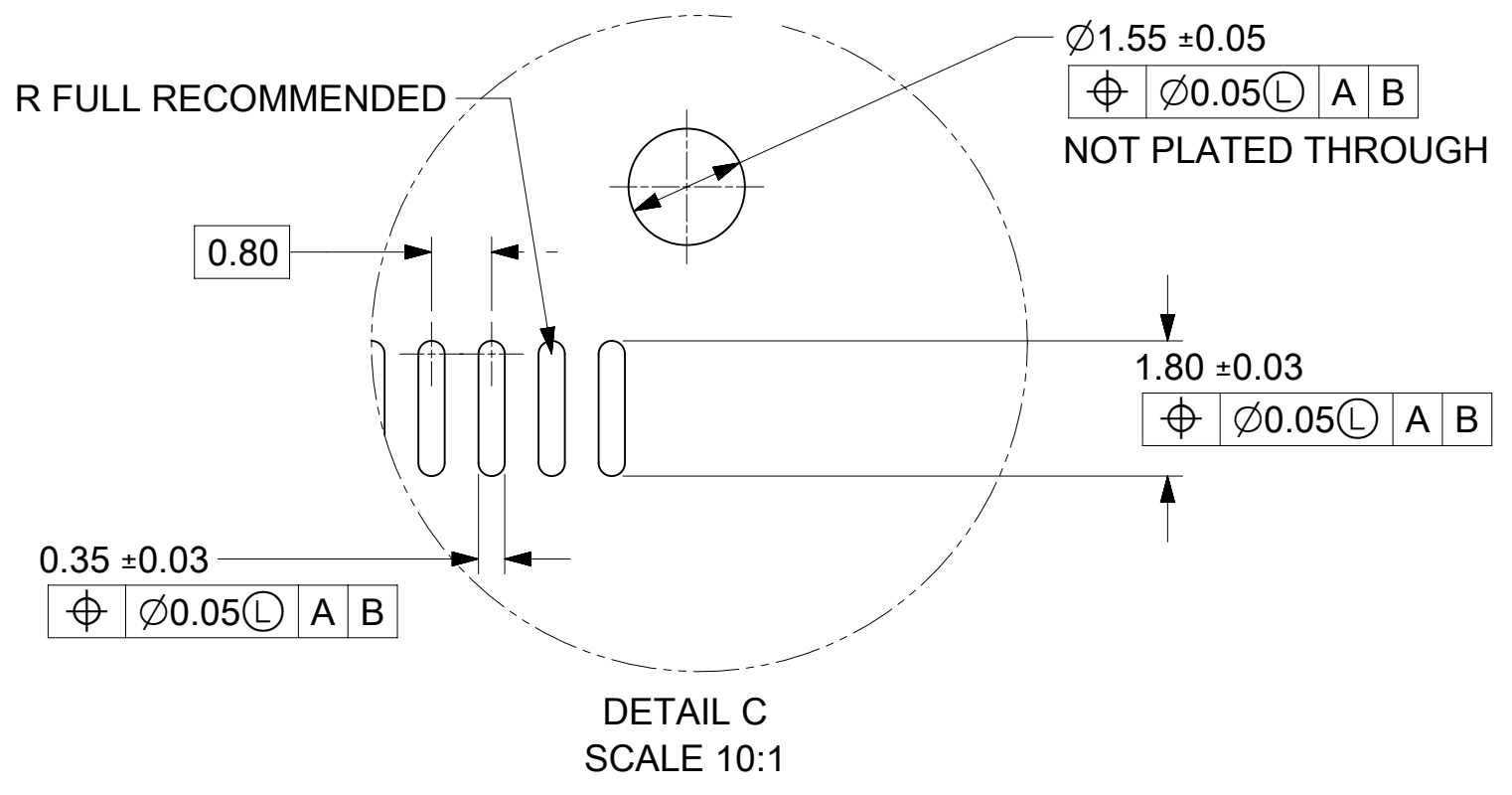
CIRCUIT SIZE	MAT'L NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
36	75577-1002	OPTION 1	17.40	15.80	16.00
68	75577-1004	OPTION 1	30.20	28.60	28.80

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS <b>mm</b>	SCALE <b>5:1</b>	CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#511698.		<b>molex</b>		
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 742551				
4 PLACES ±	±	DRWN: SANTHN 2023/03/30		PRODUCT CUSTOMER DRAWING		
3 PLACES ±	±	CHK'D: GGA 2023/05/12		DOCUMENT NUMBER		
2 PLACES ±	0.13 ±	APPR: GGA 2023/05/12		SD-75577-002		
1 PLACE ±	0.25 ±	INITIAL REVISION:		DOC TYPE DOC PART REVISION		
0 PLACES ±	±	DRWN: JLSWENSON 06/07/07		PSD 001 E1		
ANGULAR TOL ±	0.5 °	APPR: MBANAKIS 06/07/07		MATERIAL NUMBER CUSTOMER SHEET NUMBER		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING C-SIZE	SERIES 75577	SEE TABLE	GENERAL MARKET 1 OF 2



36 CIRCUIT SHOWN  
PATTERN FOR REPRESENTATION ONLY



- NOTES:
1. FOR APPROPRIATE SHELL FOOT PRINT AND KEEP OUT AREAS, SEE SD-76010-002
  2. PAD CONFIGURATION FOR FIRST MATE
  3. PAD CONFIGURATION FOR SECOND MATE
  4. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS)
  5. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION
  6. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE
  7. THESE ARE GENERIC DETAILS THAT DESCRIBES THE CONFIGURATION OF VARIOUS PCB DESIGN ELEMENTS. THE CUSTOMER MUST DETERMINE WHERE AND WHEN TO USE EACH ELEMENT TO ACCOMODATE THEIR SPECIFIC APPLICATION.
  8. CHAMFER ROUGHNESS NOT TO EXCEED 3.17µM.
  9. EDGE CARD CHAMFER NOT TO GO THROUGH GOLD PAD.

CIRCUIT SIZE	DIMENSIONS				
	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'
26	12.00	9.60	4.60	5.00	11.60
36	16.00	13.60	6.60	7.00	15.60
50	21.60	19.20	9.40	9.80	21.20
68	28.80	26.40	13.00	13.40	28.40

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DIMENSION UNITS: mm	SCALE: 5:1	CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#511698.	<b>molex</b>		
GENERAL TOLERANCES (UNLESS SPECIFIED)					
4 PLACES: ±	MM: ±	INCH: ±	SALES DRAWING IPASS VERTICAL CONNECTOR .8 MM PITCH I/O		
3 PLACES: ±	MM: ±	INCH: ±	PRODUCT CUSTOMER DRAWING		
2 PLACES: ± 0.13	MM: ±	INCH: ±	DOCUMENT NUMBER: SD-75577-002		
1 PLACE: ± 0.25	MM: ±	INCH: ±	DOC TYPE: PSD		
0 PLACES: ±	MM: ±	INCH: ±	DOC PART: 001		
ANGULAR TOL: ± 0.5°	THIRD ANGLE PROJECTION	DRAWING: C-SIZE	SHEET NUMBER: 2 OF 2		